

AMENDMENTS TO THE CLAIMS

Claims 1-17 (Canceled)

Claim 18 (Withdrawn) A method for producing a substrate holder for holding a circuit board, comprising the steps of:

placing an adhesive material on a main body to become the substrate holder; and

pressing a mold against the adhesive material while heating the mold, the mold having an undulating pattern for tackiness adjustment provided thereon.

Claim 19 (Withdrawn) The method according to claim 18, wherein

the mold includes a region in which a first undulating pattern is formed and a region in which a second undulating pattern is formed.

Claim 20 (Withdrawn) The method according to claim 19, wherein,

the mold is differentiated in level between the region in which the first undulating pattern is formed and the region in which the second undulating pattern is formed.

Claim 21 (Withdrawn) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and

blasting minute particles against the pressing surface.

Claim 22 (Withdrawn) The method according to claim 21, further comprising, before the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface.

Claim 23 (Withdrawn) The method according to claim 21, further comprising, after the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface; and
blasting another type of minute particles against the pressing surface through the mask.

Claim 24 (Withdrawn) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and
forming an undulating pattern on the pressing surface by chemical etching.

Claims 25-26 (Canceled)

Claim 27 (Currently Amended) A substrate holder for holding a circuit board, comprising:

a main body; and

a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:

a first adhesive holding region which has first ~~second~~-surface coarseness ~~different from the first surface coarseness~~ and is operable to hold the circuit board with a first tackiness which corresponds to the first surface coarseness; and

a second adhesive holding region which has second surface coarseness different from the first surface coarseness and is operable to hold the circuit board with a second tackiness which corresponds to the second surface coarseness and is different from the first tackiness, said first and second adhesive holding regions being coplanar and capable of holding the circuit board in cooperation;

wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body; ~~and~~

wherein both a tackiness between the first adhesive holding region and the main body and a tackiness between the second adhesive holding region and the main body are larger than the first tackiness and the second tackiness; and

wherein a through hole for receiving a pin is located in the first adhesive holding region so that the through hole is usable by the pin for peeling off the circuit board.

Claim 28 (Previously Presented) The substrate holder of claim 27, and further comprising an adhesive material provided on said main body, said first adhesive holding region and said second adhesive holding region being on a surface of said adhesive material.

Claim 29 (Previously Presented) The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are within one area of the adhesive material on said main body.

Claim 30 (Previously Presented) The substrate holder of claim 29, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

Claim 31 (Canceled)

Claim 32 (Previously Presented) The substrate holder of claim 28, wherein the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and the first adhesive holding region and the second adhesive holding region have different surface undulation characteristics.

Claims 33-37 (Canceled)

Claim 38 (Previously Presented) The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness and the second adhesive holding region is confined within the first adhesive holding region.

Claim 39 (Currently Amended) The substrate holder of claim 27, wherein the first tackiness is less than the second tackiness ~~and a through hole for receiving a pin is in the first adhesive region, the through hole being usable by the pin for peeling off the circuit board.~~

Claim 40 (Previously Presented) The substrate holder of claim 39, wherein an air outlet is provided in the second adhesive region.

Claim 41 (Withdrawn) The substrate holder of claim 29, wherein the first tackiness is less than the second tackiness and the first adhesive holding region is confined within the second adhesive holding region.

Claim 42 (Previously Presented) The substrate holder of claim 27, wherein the holding surface comprises a plurality of sets of the first adhesive holding region and the second adhesive holding region.

Claim 43 (Previously Presented) The substrate holder of claim 28, wherein the adhesive material comprises silicone rubber, polyurethane rubber or fluorine rubber.

Claim 44 (Currently Amended) A pallet for carrying a circuit board comprising:
a main body; and
a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface, wherein the holding surface includes:
a first adhesive holding region which has first surface coarseness and is operable to hold the circuit board with a first tackiness which corresponds to the first surface coarseness; and

a second adhesive holding region which has second surface coarseness different from the first surface coarseness and is operable to hold the circuit board with a second tackiness which corresponds to the second surface coarseness and is different from the first tackiness, said first and second adhesive regions being coplanar and capable of holding the circuit board in cooperation;

wherein the first adhesive holding region and the second adhesive holding region are arranged parallel to the surface of said main body; and

wherein both a tackiness between the first adhesive holding region and the main body and a tackiness between the second adhesive holding region and the main body are larger than the first tackiness and the second tackiness;

wherein a through hole for receiving a pin is located in the first adhesive holding region so that the through hole is usable by the pin for peeling off the circuit board.